

APPLICATION DATA SHEET

APPLICATION INFORMATION

Application Type:: REGULAR
Subject Matter:: UTILITY
CD-ROM or CD-R?: NONE
Title:: EPOXY RESIN COMPOSITION FOR
SEMICONDUCTOR SEALING AND
SEMICONDUCTOR DEVICE
Attorney Docket Number:: 251428US90

INVENTOR INFORMATION

Applicant Authority Type:: INVENTOR
Status:: FULL CAPACITY
Given Name:: Masakatsu
Family Name:: MAEDA
Street of Mailing Address:: c/o Utsunomiya Plant, SUMITOMO
BAKELITE CO., LTD., 20-7, Kiyohara-
Kogyodanchi
City of Mailing Address:: Utsunomiya-shi
State or Province of Mailing Address:: Tochigi
Country of Mailing Address:: Japan
Postal or Zip Code of Mailing Address:: 321-3231

CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 22850

REPRESENTATIVE INFORMATION

Representative Customer Number:: 22850

FOREIGN PRIORITY INFORMATION

Application Number:	Country::	Filing Date::	Priority Claimed::
2003-123879	Japan	04/28/03	YES

ASSIGNMENT INFORMATION

Assignee Name:: SUMITOMO BAKELITE CO., LTD.

Street of Mailing Address:: 5-8, Higashishinagawa 2-chome,
Shinagawa-ku
City of Mailing Address:: Tokyo
Country of Mailing Address:: Japan
Postal or Zip Code of Mailing Address:: 140-0002